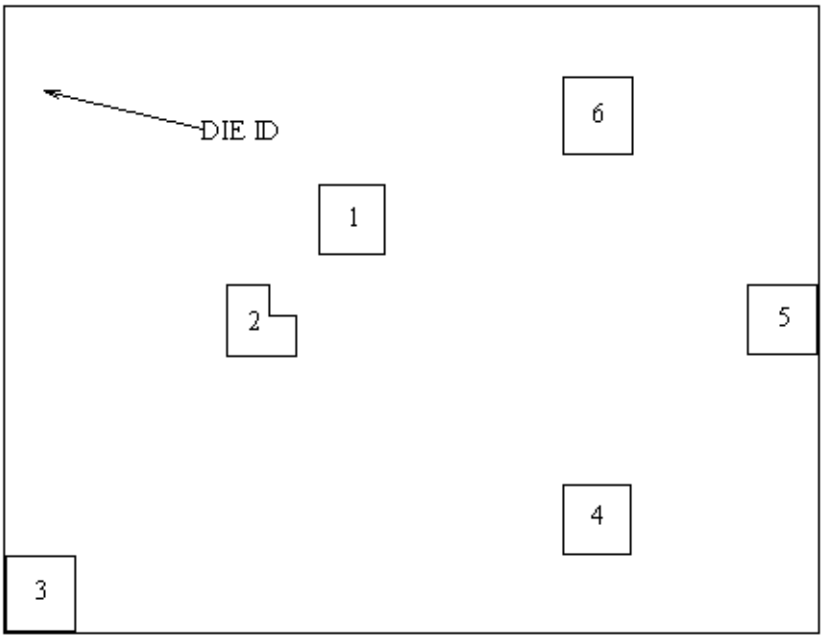
LM320KG-5 MDC MWC
SERIES 3-TERMINAL NEGATIVE REGULATORS

March 19,2002

DIE LAYOUT (E-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	120E	Bond Pad Opening Size (min)	183µm x 193µm
Die Step	E	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	100mm	Back Side Metal	Gold
Die Size (Drawn)	1753µm x 2261µm 69mils x 89mils	Back Side Connection	INPUT
Thickness	330µm Nominal		
Min Pitch	768µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (E -Step)

(Referenced to die center, coordinates in µm) NC = No Connection

SIGNAL NAME	PAD# NUMBER	X/Y CORRDINATES X	Y	PAD SIZE X		Y
OUTPUT	1	-178	279	183	x	193
NC	2	-433	-1	191	x	201
GND	3	-1054	-768	193	x	206
INPUT	4	507	-558	191	x	194
OUTPUT	5	1029	0	193	x	193
INPUT	6	508	570	193	x	216

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